U.S. DEPARTMENT OF COMMERCE

PATENT AND TRADEMARK OFFICE

AU: 2814

EXAMINER'S CASE ACTION WORKSHEET

Application No. 10/039,219				Legal Instrument Examiner	
CHE	CK TYPE OF ACTION				DATE OF COUNT
	▶Non-Final Rejection		Restriction/Election Only		Final Rejection
	Ex Parte Quayle		Allowance		Advisory Action
	Examiner's Answer		Reply Brief Noted		Non-Entry of Reply Brief
	Defective Notice of Appeal		Interference Disposal SPE(Approval for Disposal)		Suspension (Examiner-Initiated) SPE (initial)
	Defective Appeal Brief		SIR Disposal (use only after FAOM)		Supplemental Examiner's Amendment
	Miscellaneous Office Letter (With Shortened Statutory Period Set)		Notice of Non-Responsive Amendment (With One Month Time Period set)		Miscellaneous Office Letter (No Response Period Set)
	Abandonment after BPAI Decision		Supplemental Action (excluding Examiner's Answer)		Response to Rule 312 Amendment
	Letter Restarting Period for Response (e.g., Missing References)		Interview Summary		Authorization to Change Previous Office Action SPE: (Initial)
	Abandonment		Express Abandonment Date:		Other Specify:

Examiner's Name: DiLinh Nguyen







UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER OF PATENTS AND TRADEMARKS Washington, D.C. 20231 www.iispio.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.		
10/039,219	01/02/2002	Chun-Chi Ke	56843 (71987)	2017		
7	7590 02/28/2003					
Mr. Peter F. 0			EXAM	EXAMINER		
101 Federal St			NGUYEN, DILINH P			
Boston, MA (J2110		ART UNIT	PAPER NUMBER		
			2814			
			DATE MAILED: 02/28/2003	DATE MAILED: 02/28/2003		

Please find below and/or attached an Office communication concerning this application or proceeding.

				/
		Application No.	Applicant(s)	#
•	Office Antinu C	10/039,219	KE ET AL.	
•	Office Action Summary	Examin r	Art Unit	
		DiLinh Nguyen	2814	
Period for	- The MAILING DATE of this communication app r Reply	ears on the cover sheet with the	correspondence address	
I HE N - Extens after S - If the p - If NO p - Failure - Any re	DRTENED STATUTORY PERIOD FOR REPLY MAILING DATE OF THIS COMMUNICATION. sions of time may be available under the provisions of 37 CFR 1.13 GIX (6) MONTHS from the mailing date of this communication. period for reply specified above is less than thirty (30) days, a reply period for reply is specified above, the maximum statutory period we to reply within the set or extended period for reply will, by statute, uply received by the Office later than three months after the mailing dipatent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be tir within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from	mely filed ys will be considered timely. I the mailing date of this communication.	
1)⊠	Responsive to communication(s) filed on 11 F	ebruary 2003 .		
2a)[is action is non-final.		
	Since this application is in condition for allowa closed in accordance with the practice under ton of Claims	nce except for formal matters, p	rosecution as to the merits is 453 O.G. 213.	
4) 🖂 (Claim(s) $1-8$ is/are pending in the application.			
4	a) Of the above claim(s) <u>5-8</u> is/are withdrawn f	rom consideration.		
5) (Claim(s) is/are allowed.			
6)⊠ (Claim(s) <u>1-4</u> is/are rejected.			
7) 🗌 (Claim(s) is/are objected to.			
8) (Applicatio	Claim(s) are subject to restriction and/or on Papers	election requirement.		
	he specification is objected to by the Examiner			
	he drawing(s) filed on is/are: a)□ accept		miner	
	Applicant may not request that any objection to the			
11) 🔲 Ti	he proposed drawing correction filed on			
	If approved, corrected drawings are required in repl			
	he oath or declaration is objected to by the Exa			
Priority un	nder 35 U.S.C. §§ 119 and 120			
13)⊠ A	Acknowledgment is made of a claim for foreign	priority under 35 U.S.C. § 119(a)-(d) or (f)	
	All b) Some * c) None of:	, , ,	, (.,, -, (.,,	
1		have been received.		
2	Certified copies of the priority documents		on No.	
	Copies of the certified copies of the priori application from the International Bure te the attached detailed Office action for a list of	ty documents have been receive eau (PCT Rule 17.2(a)).	ed in this National Stage	
	knowledgment is made of a claim for domestic			
	☐ The translation of the foreign language prov			
15) Ac	knowledgment is made of a claim for domestic			
Attachment(s		_		
2) Notice o 3) Informa	of References Cited (PTO-892) of Draftsperson's Patent Drawing Review (PTO-948) tion Disclosure Statement(s) (PTO-1449) Paper No(s) <u>2</u> .		(PTO-413) Paper No(s) Patent Application (PTO-152)	
S. Patent and Trade TO-326 (Rev.		on Summary	Part of Paper No. 6	

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DETAILED ACTION

Election/Restrictions

Applicant's election with traverse of Group I, claims 1-4 in Paper No. 5 is acknowledged. The traversal is on the ground(s) that claim 1 is similar to limitations of claim 5 and the examiner has failed to demonstrate that the product as claimed can be made by another and materially different process. This is not found persuasive because:

- Claims 1-4, drawn to a semiconductor device, classified in class 257, subclass 678+.
- II. Claims 5-8, drawn to a method for forming a semiconductor device, classified in class 438, subclass 106.

The inventions are distinct, each from the other because:

Inventions I and II are related as process of making and product made. The inventions are distinct if either or both of the following can be shown: (1) that the process as claimed can be used to make other and materially different product or (2) that the product as claimed can be made by another and materially different process (MPEP § 806.05(f)). In the instant case, the product as claimed can be made by different process, it would be possible to form a second tape to the encapsulant prior to the step of adhering to the first side of the lead frame.

Because these inventions are distinct for the reasons given above and have acquired a separate status in the art as shown by their different classification, restriction for examination purposes as indicated is proper.

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The requirement is still deemed proper and is therefore made FINAL.

Title

The title of the invention is not descriptive. A new title is required that is clearly indicative of the invention to which the claims are directed.

Specification

Claim 1 is objected to because of the following informalities:

In line 11 of claim 1, the phrase: "...a semiconductor chip mounted in the cavity..." should be changed to the semiconductor chip mounted in the cavity.

In line 13, the phrase: "...a plurality of bonding wires..." should be changed to the plurality of bonding wires or bonding wires.

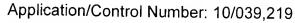
Appropriate correction is required.

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1-2 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kitaoka et al. (U.S. Pat. 5523608) in view of Mizue et al. (U.S. Pat. 6315465).

Kitaoka et al. disclose a semiconductor device (fig. 1, column 3, lines 45 et seq.) comprising:

a lead frame having a first side and a second side, and formed with a die pad 7 and a plurality of leads surrounding the die pad, wherein the leads are each defined into



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an inner lead 3, an outer lead 4 and a middle portion positioned between the inner lead and the outer lead;

an encapsulant 8 for encapsulating the lead frame with the outer leads being exposed, wherein a cavity is formed in the encapsulant for exposing the die pad and the inner leads on the first side of the lead frame, allowing a semiconductor chip 1 and bonding wires 5 to be received in the cavity;

the semiconductor chip 1 mounted in the cavity on the die pad of the first side of the lead frame;

bonding wires 5 formed in the cavity for electrically connecting the semiconductor chip to the inner leads of the lead frame; and

a lid 11adhered onto the encapsulant for covering an opening of the cavity.

Kitaoka et al. fail to disclose each of the middle portions extends outwardly at sides thereof to form protrusions.

Mizue et al. disclose a semiconductor device (fig. 3) comprising:

a lead frame, wherein the leads are each defined into an inner lead, an outer lead and a middle portion positioned between the inner lead and the outer lead, and each of the middle portions extends outwardly at sides thereof to form protrusions. Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the device of Kitaoka et al. to maintain the stability and reliability for the semiconductor device, as shown by Mizue et al.

 Regarding claim 2, it would have been an obvious matter of design choice to form the middle portions of the leads are arranged in a manner that spacing

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between the adjacent middle portions is 0.10 mm, or equal to or smaller than 0.15 mm.

3. Claims 3-4 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kitaoka et al. (U.S. Pat. 5523608) in view of Mizue et al. (U.S. Pat. 6315465) and further in view of Waki et al. (U.S. Pat. 5479051).

Kitaoka et al. and Mizue et al. fail to disclose a first tape adhered to the second side of the lead frame and a second tape adhered to the first side of the lead frame.

Waki et al. disclose a semiconductor device (figs. 3A and 7A) comprising :

a tape 12 adhered to the first side of the lead frame in a manner free of interference with arrangement of the bonding wires (fig. 3A, column 4, lines 14-22) and plurality of tapes 22a and 22b adhered to the second side of the lead frame (fig. 7A). Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the device of Kitaoka et al. and Mizue et al. to increase the quality and reliability for the lead frame, as shown by Waki et al.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to DiLinh Nguyen whose telephone number is (703) 305-6983. The examiner can normally be reached on 8:00AM - 6:00PM (M-F).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (703) 308-4918. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 308-7722 for regular communications and (703) 308-7724 for After Final communications.

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Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

DLN February 19, 2003

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